



100% Material Declaration Data Sheet BGG432

PK198 (v1.0.1) January 8, 2007

Material Declaration Data Sheet

Average Weight: 8.7852 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0585	0.67%
	Silicon	7440-21-3	100.00		0.0585	
Die Attach Material					0.007	0.07%
	Resin	Trade Secret	25.00		0.002	
	Silver	7440-22-4	75.00		0.005	
Mold Compound					0.3009	3.42%
	Resin	Trade Secret	26.00		0.078	
	Silica	60676-86-0	74.00		0.233	
Dam					0.0098	0.11%
	Proprietary	Trade Secret	27.00		0.002646	
	Silica	60676-86-0	73.00		0.007154	
Laminate					0.8377	9.54%
	Copper	7440-50-8	15.51	Metal Layer	0.130	
	Nickel	7440-02-0	0.95	Metal Layer	0.008	
	Gold	7440-57-5	0.22	Metal Layer	0.002	
	Board	Trade Secret	61.24		0.513	
	Solder Mask (EP)	Trade Secret	22.08		0.185	
Heat Sink					6.8302	77.75%
	Copper	7440-50-8	100.00		6.8302	
Heat Sink Plating					0.2920	3.32%
	Nickel	7440-02-0	100.00		0.2920	
Gold Wire					0.0191	0.22%
	Gold	7440-57-5	100.00		0.0191	
Solder Balls					0.430	4.90%
	Tin	7440-31-5	95.50		0.411	
	Silver	7440-22-4	4.00		0.017	
	Copper	7440-50-8	0.50		0.002	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.
1/8/07	1.0.1	Corrected Gold Wire CAS# entry.